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(54) Title: DIE PRESS PROCESS FOR MANUFACTURING A Z-DIRECTED COMPONENT FOR A PRINTED CIRCUIT BOARD

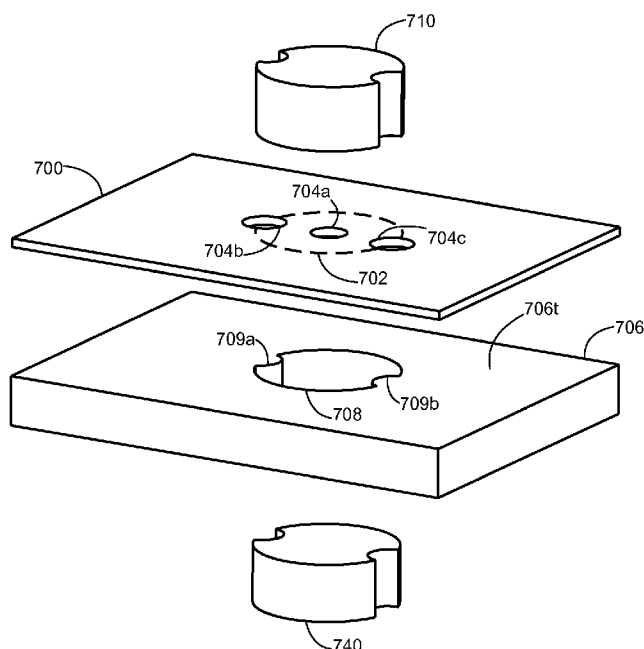


Figure 15

(57) Abstract: A method for manufacturing a Z-dir-
ected component for insertion into a mounting hole
in a printed circuit board according to one example
embodiment includes punching a plurality of seg-
ments out of at least one sheet of substrate material
to form a plurality of layers of the Z-directed com-
ponent. A channel is formed through the substrate
material either before or after the segments are
punched. At least one of the formed layers includes
at least a portion of the channel. A conductive ma-
terial is applied to at least one surface of at least one
of the formed layers. A stack of the formed layers
is combined to form the Z-directed component.



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